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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

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Norio FUKASAWA et al.

NOV 12 1999

Group Art Unit: 2812

Serial No.: 09/029,608

TECHNOLOGY CENTER 2800

Filed: May 15, 1998

For: METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,
SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE

SECOND SUPPLEMENTAL PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

June 4, 1999

Sir:

Further to the Supplemental Preliminary Amendment filed on February 26, 1999, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 13-17 without prejudice or disclaimer and add new claims 103-108 as follows:

--103. A mold for fabricating a semiconductor device comprising:

a first mold; and

a second mold which is located so as to face the first mold,

the second mold including a first half body having a shape corresponding to a shape of a substrate, and a second half body which is provided so as to surround the first half body and can be elevated with respect to the first half body,

the first and second half bodies cooperating with each other so that a cavity to be filled